

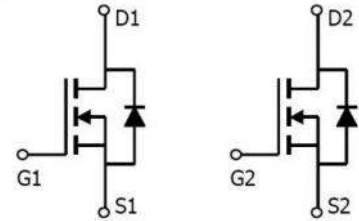
Dual N-Channel Enhancement Mosfet

Features

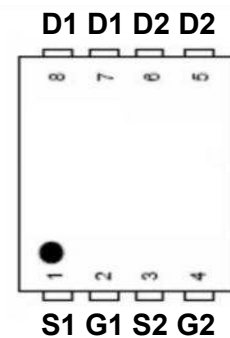
- 100V,40A
 $R_{DS(on)}$ (TYP: 15.8m Ω) < 21m Ω @ $V_{GS}=10V$
 $R_{DS(on)}$ (TYP: 19.5m Ω) < 25m Ω @ $V_{GS}=4.5V$
- Split Gate Trench Technology
- Lead free product is acquired
- Excellent $R_{DS(on)}$ and Low Gate Charge
- P/N suffix V means AEC-Q101 qualified, e.g:RMD40N100DFV
- Halogen-free

Application

- High Frequency Switching
- Synchronous Rectification



Schematic diagram



pin Assignment

Package Marking and Ordering Information

Device Marking	Device	Package	Packaging Code	Reel Size	Quantity(Pcs)	Carton(Pcs)
D40N100	RMD40N100DFV	DFN5X6	-W	13inch	5000	80000

ABSOLUTE MAXIMUM RATINGS ($T_J=25^{\circ}C$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	100	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current ($T_c = 25^{\circ}C$)	I_D	40	A
Continuous Drain Current ($T_c = 100^{\circ}C$)	I_D	30	A
Pulsed Drain Current ⁽¹⁾	I_{DM}	160	A
Single Pulsed Avalanche Energy ⁽²⁾	E_{AS}	100	mJ
Power Dissipation	P_D	81	W
Thermal Resistance from Junction to Case	$R_{\theta JC}$	1.85	$^{\circ}C/W$
Thermal Resistance from Junction to Ambient	$R_{\theta JA}$	65	$^{\circ}C/W$
Junction Temperature	T_J	175	$^{\circ}C$
Storage Temperature	T_{STG}	-55~ +175	$^{\circ}C$

MOSFET ELECTRICAL CHARACTERISTICS($T_J=25^{\circ}\text{C}$ unless otherwise noted)

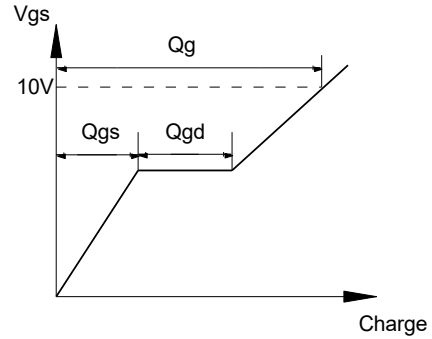
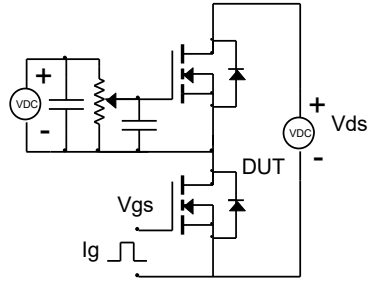
Parameter	Symbol	Test Condition	Min	Type	Max	Unit
Static Characteristics						
Drain-source breakdown voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	100	-	-	V
Zero gate voltage drain current	I_{DSS}	$V_{DS} = 100V, V_{GS} = 0V$	-	-	1	μA
Gate-body leakage current	I_{GSS}	$V_{GS} = \pm 20V, V_{DS} = 0V$	-	-	± 100	nA
Gate threshold voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	1.0	1.8	2.5	V
Drain-source on-resistance	$R_{DS(on)}$	$V_{GS} = 10V, I_D = 20A$	-	15.8	21.0	m Ω
		$V_{GS} = 4.5V, I_D = 10A$	-	19.5	25.0	
Gate Resistance	R_g	$V_{DS} = V_{GS} = 0V, f = 1MHz$	-	1.44	-	Ω
Dynamic characteristics						
Input Capacitance	C_{iss}	$V_{DS} = 50V, V_{GS} = 0V, f = 1MHz$	-	1016	-	pF
Output Capacitance	C_{oss}		-	194	-	
Reverse Transfer Capacitance	C_{rss}		-	3.4	-	
Switching characteristics						
Turn-on delay time	$t_{d(on)}$	$V_{DD} = 50V, I_D = 40A,$ $V_{GS} = 10V,$ $R_G = 3.3\Omega$	-	27	-	ns
Turn-on rise time	t_r		-	49	-	
Turn-off delay time	$t_{d(off)}$		-	225	-	
Turn-off fall time	t_f		-	94	-	
Total Gate Charge	Q_g	$V_{DS} = 50V, I_D = 40A,$ $V_{GS} = 10V$	-	13.8	-	nC
Gate-Source Charge	Q_{gs}		-	4.0	-	
Gate-Drain Charge	Q_{gd}		-	2.3	-	
Source-Drain Diode characteristics						
Diode Forward voltage	V_{DS}	$V_{GS} = 0V, I_S = 20A$	-	-	1.0	V
Diode Forward current	I_S		-	-	40	A
Reverse Recovery Charge	Q_{rr}	$I_F = 20A, di/dt = 100A/\mu s$		32		nC
Reverse Recovery Time	T_{rr}	$I_F = 20A, di/dt = 100A/\mu s$		33		ns

Notes:

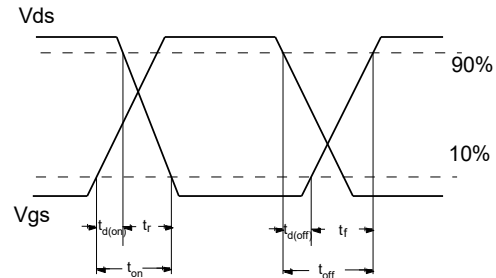
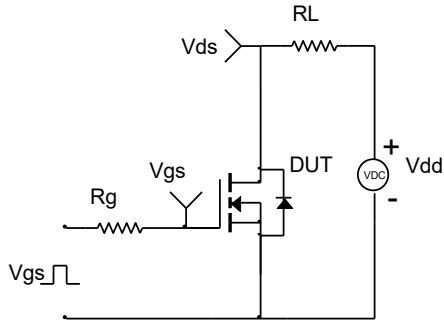
1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature
2. EAS condition: $T_J = 25^{\circ}\text{C}$, $V_{DD} = 20V$, $I_{AS} = 20A$, $R_G = 25\Omega$, $L = 0.5mH$
3. The value of $R_{\theta JA}$ Mounted on FR4 Board (2 5.4mm*25.4mm*t1.6mm) With 2oz Copper, $T_a = 25^{\circ}\text{C}$

Test Circuit

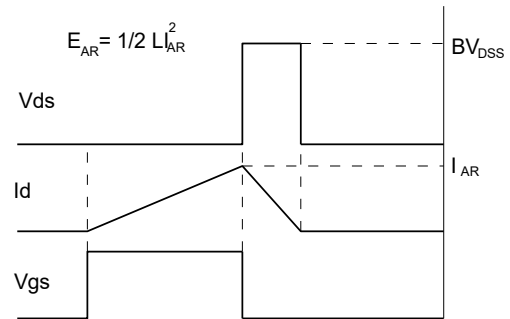
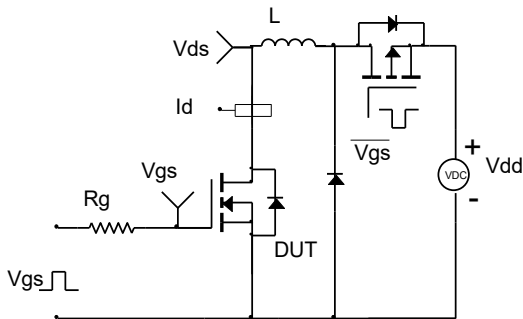
Gate Charge Test Circuit & Waveform



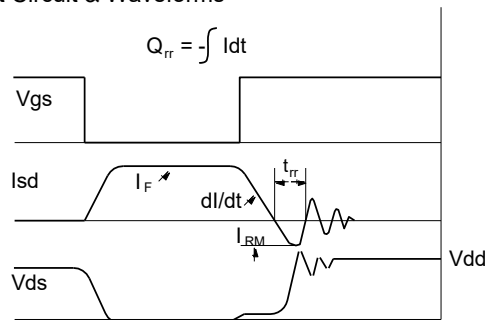
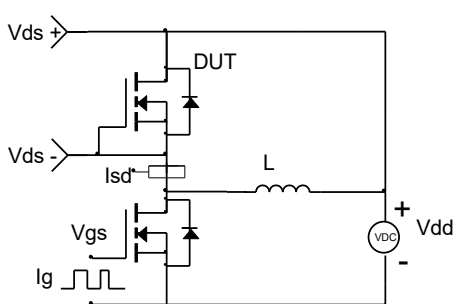
Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms



RATING AND CHARACTERISTICS CURVES (RMD40N100DFV)

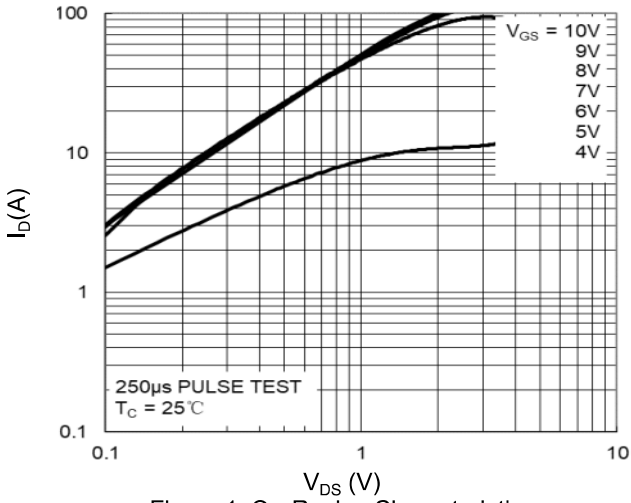


Figure 1: On-Region Characteristics

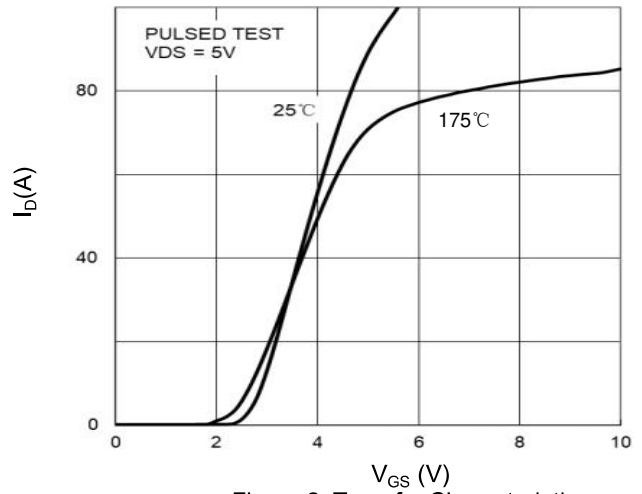


Figure 2: Transfer Characteristics

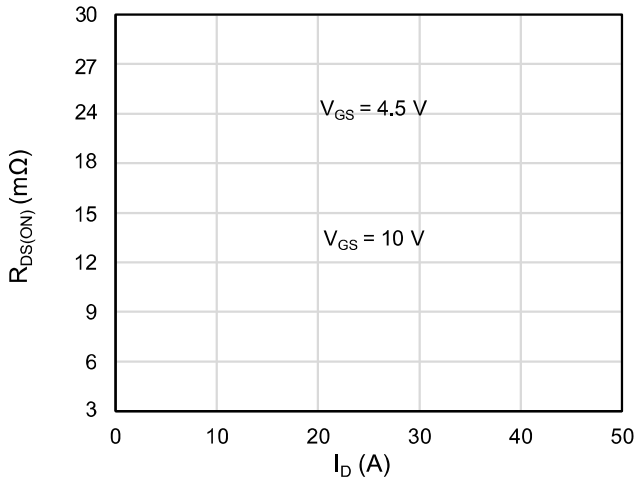


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

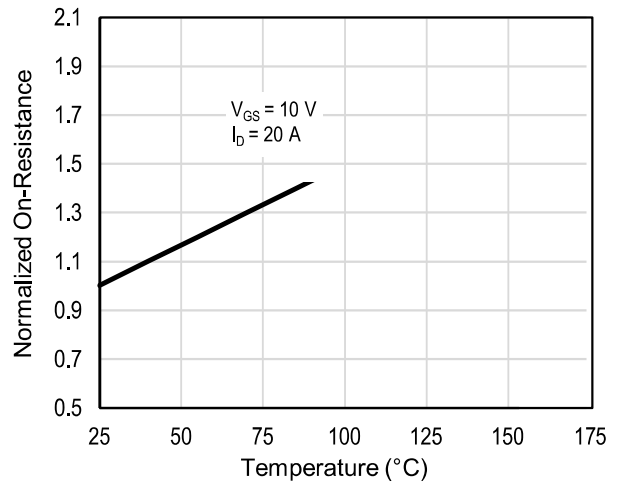


Figure 4: On-Resistance vs. Junction Temperature

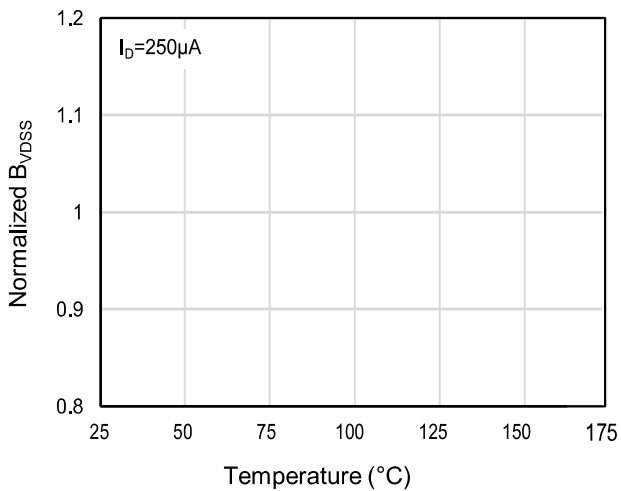


Figure 5: Breakdown Voltage vs. Junction Temperature

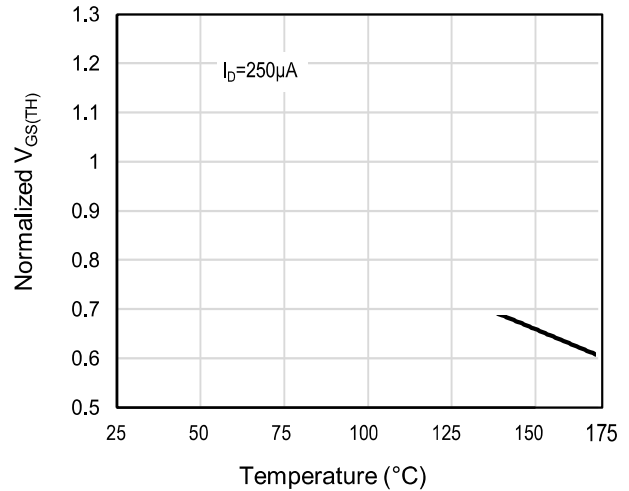


Figure 6: Threshold Voltage vs. Junction Temperature

RATING AND CHARACTERISTICS CURVES (RMD40N100DFV)

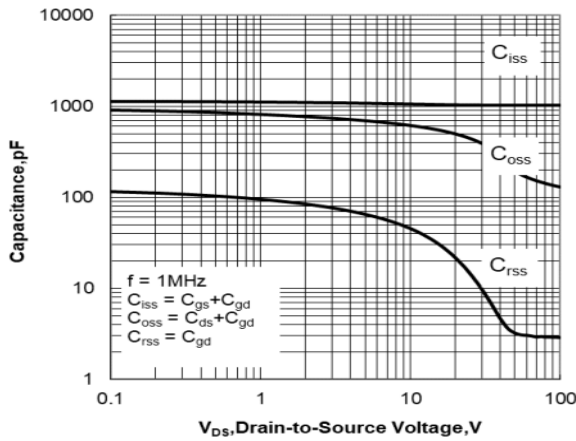


Figure 7. Capacitance Characteristics

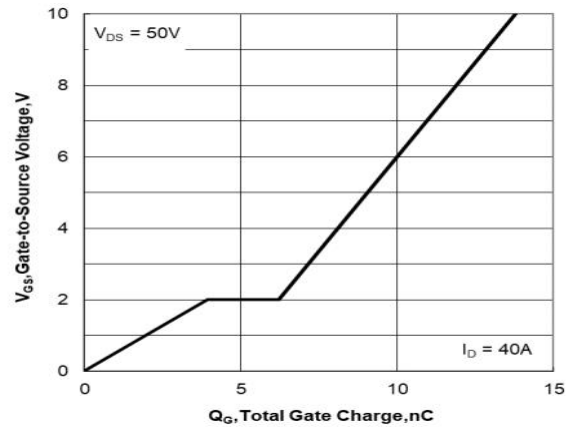


Figure 8. Gate Charge Characteristics

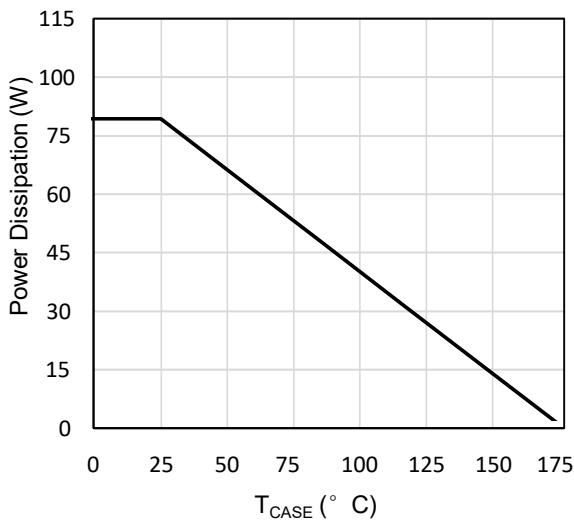


Figure 9. Maximum Continuous Drain Current vs Case Temperature

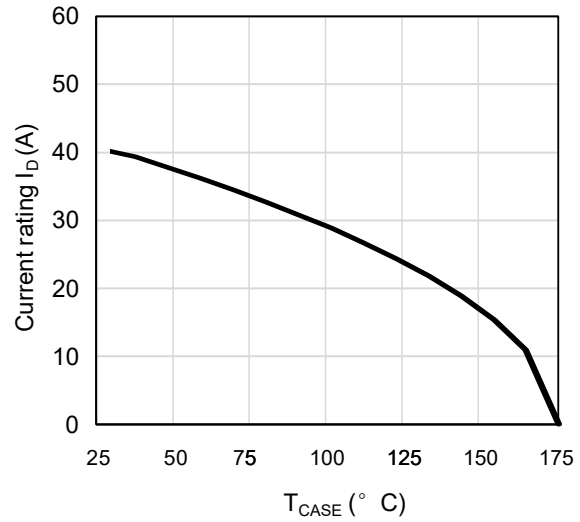


Figure 10. Maximum Power Dissipation vs Case Temperature

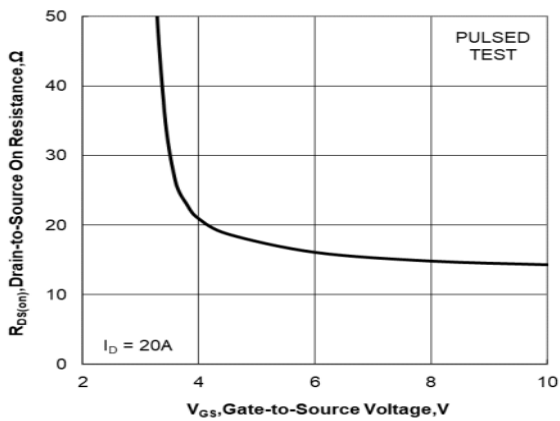


Figure 11. Drain-to-Source On Resistance vs Gate Voltage and Drain Current

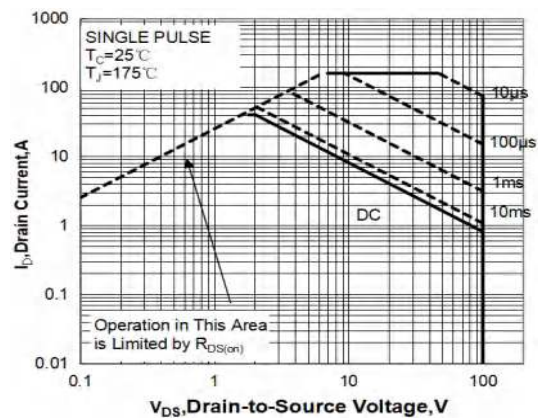


Figure 12. Maximum Safe Operating Area

RATING AND CHARACTERISTICS CURVES (RMD40N100DFV)

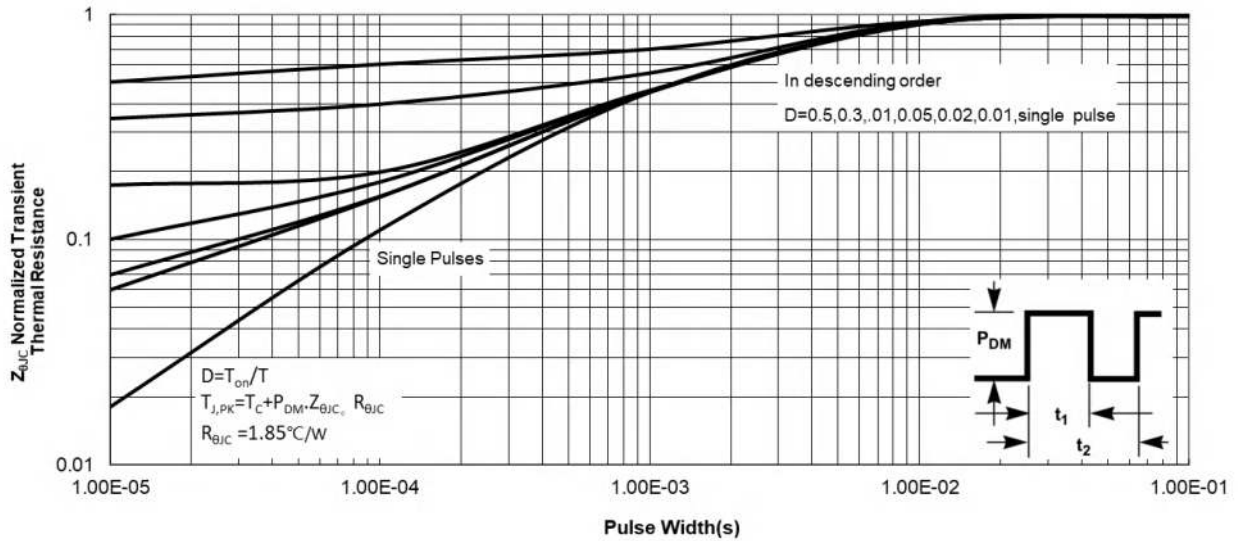
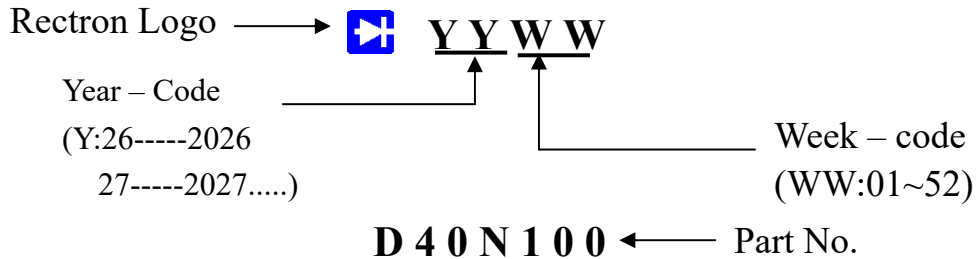


Figure.13: Maximum Effective Transient Thermal Impedance, Junction-to-Case

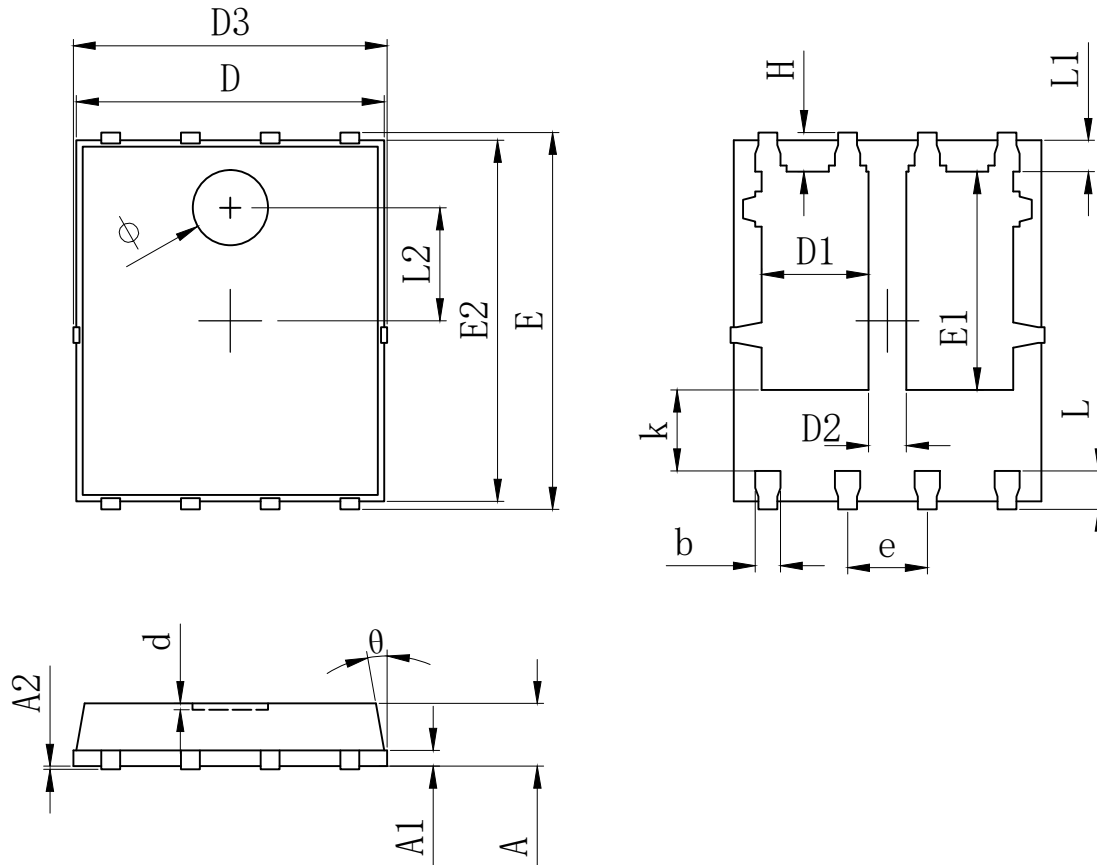


RECTRON

Marking on the body



DFN5X6 Package Information



SYMBOL	MILLIMETER		
	MIN	Typ.	MAX
A	0.900	1.000	1.100
A1	0.254 REF.		
A2	0 ⁺ 0.05		
D	4.824	4.900	4.976
D1	1.605	1.705	1.805
D2	0.500	0.600	0.700
D3	4.924	5.000	5.076
E	5.924	6.000	6.076
E1	3.375	3.475	3.575
E2	5.674	5.750	5.826
b	0.350	0.400	0.450
e	1.270 TYP.		
L	0.534	0.610	0.686
L1	0.424	0.500	0.576
L2	1.800 REF.		
k	1.190	1.290	1.390
H	0.549	0.625	0.701
θ	8°	10°	12°
ϕ	1.100	1.200	1.300
d			0.100

DISCLAIMER NOTICE

Rectron Inc reserves the right to make changes without notice to any product specification herein, to make corrections, modifications, enhancements or other changes. Rectron Inc or anyone on its behalf assumes no responsibility or liability for any errors or inaccuracies. Data sheet specifications and its information contained are intended to provide a product description only. "Typical" parameters which may be included on RECTRON data sheets and/ or specifications can and do vary in different applications and actual performance may vary over time. Rectron Inc does not assume any liability arising out of the application or use of any product or circuit.

Rectron products are not designed, intended or authorized for use in medical, life-saving implant or other applications intended for life-sustaining or other related applications where a failure or malfunction of component or circuitry may directly or indirectly cause injury or threaten a life without expressed written approval of Rectron Inc. Customers using or selling Rectron components for use in such applications do so at their own risk and shall agree to fully indemnify Rectron Inc and its subsidiaries harmless against all claims, damages and expenditures.